

Title (en)

Recyclable hot melt adhesive compositions.

Title (de)

Wiederverwendbare Schmelzklebstoffzusammensetzung.

Title (fr)

Composition adhésive thermofusible recyclable.

Publication

EP 0302394 A2 19890208 (EN)

Application

EP 88112258 A 19880728

Priority

US 8200987 A 19870805

Abstract (en)

Recyclable hot melt adhesive compositions suitable for plastic bonding may be prepared from styrene-ethylene-butylene-styrene tri-block and/or styrene-ethylene-butylene di-block copolymers which are tackified with at least one hydrogenated resin based on alpha-methyl styrene, vinyl toluene, styrene, coumarone-indene, dicyclopentadiene or mixtures thereof, optionally containing small amounts of white mineral oil or similar diluent. In addition, the adhesive may or may not include minor amounts of the above-described pure monomer resins (specifically composed of styrene, alpha methyl styrene or vinyl toluene or mixtures thereof) in their non-hydrogenated form to serve as end block reinforcing resins.

IPC 1-7

C08J 5/12; **C08L 53/00**; **C08L 53/02**; **C09J 125/00**

IPC 8 full level

C08L 51/06 (2006.01); **C09J 7/02** (2006.01); **C09J 151/06** (2006.01); **C09J 153/00** (2006.01); **C09J 153/02** (2006.01)

CPC (source: EP US)

C09J 153/025 (2013.01 - EP US); **Y10T 428/1303** (2015.01 - EP US); **Y10T 428/1352** (2015.01 - EP US); **Y10T 428/1397** (2015.01 - EP US); **Y10T 428/2826** (2015.01 - EP US); **Y10T 428/2883** (2015.01 - EP US); **Y10T 428/31786** (2015.04 - EP US); **Y10T 428/31797** (2015.04 - EP US); **Y10T 428/31899** (2015.04 - EP US); **Y10T 428/31993** (2015.04 - EP US)

Cited by

US5418052A; US6230452B1; EP0428017A3; EP1700895A1; CN107109173A; AU2015364517B2; US6632882B2; US6350810B1; US10351298B2; US9902884B2; WO0056824A1; WO2016100725A1

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DOCDB simple family (application)

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